

Title Terms: MANUFACTURE; METHOD; MEMBRANE; FORMING; COMPOSITION;
INTERLAYER; INSULATE; MEMBRANE; SEMICONDUCTOR; ELEMENT; ONE; KIND; SILANE
; COMPOUND; HYDROLYSIS; PRESENCE; NITROGEN; ONIUM; SALT
Derwent Class: A26; A85; E11; G02; L03; U11
International Patent Class (Main): C09D-183/04
International Patent Class (Additional): C09D-183/02; C09D-183/14
File Segment: CPI; EPI

→ 1/5/2

DIALOG(R)File 352:Derwent WPI
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WPI Acc No: 2002-133815/200218
XRAM Acc No: C02-041195
XRPX Acc No: N02-101222

Film for interlayer insulating film, used in semiconductor elements, has
specific film density

Patent Assignee: JSR CORP (JAPS)
Number of Countries: 001 Number of Patents: 001
Patent Family:

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JP 2001203197	A	20010727	JP 200012513	A	20000121	200218 B

Priority Applications (No Type Date): JP 200012513 A 20000121

Patent Details:

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Abstract (Basic): JP 2001203197 A

NOVELTY - A film has a film density of 0.5 - 1.4 g/cm3.

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DETAILED DESCRIPTION - The film consists of formula (1).

x=1.3 - 1.9;

y=0.2 - 8.0;

z=0.6 - 7.0

USE - The method forms the film for an interlayer insulating film
for use in a semiconductor element.

ADVANTAGE - The film has superior dielectric constant and
mechanical strength.

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Title Terms: FILM; INTERLAYER; INSULATE; FILM; SEMICONDUCTOR; ELEMENT;
SPECIFIC; FILM; DENSITY

Derwent Class: A82; A85; G02; L03; U11

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Composition for film formation, comprises product obtained by hydrolyzing
and condensing at least one silane compound and an organic solvent